

SCREEN PRINTING SQUEEGEE FOR APPLYING SOLDER PASTE

Abstract

Apparatus and methods for applying solder paste to circuits, such as
5 integrated circuits, are disclosed. The apparatus and methods comprise a
squeegee blade having a pair of elongated face sides spaced apart by a selected
thickness and a corresponding pair of elongated substantially parallel narrow
sides spaced apart by a selected width. The elongated face sides and elongated
narrow sides join together to form squeegee operating edges. The squeegee
10 blade is free of mounting aperture as to provide four operating edges. The
squeegee blade is mounted to a resilient clamping structure which applies a
regular and controlled gripping force so as to avoid deformation of the squeegee
blade edge due to excessive mounting force. The plurality of fasteners are
received by the clamping structure for adjusting the gripping force to the
15 squeegee blade.